

The Second International Conference on Power Electronics Systems and Applications



Organized By :

Power Electronics Research Centre The Hong Kong Polytechnic University



Co-organized By :

The Asia Pacific Chamber of Electrical & Electronic Industries Ltd.

Sponsor By :



ALTANA
Electrical Insulation



MICROMETALS
IRON POWDER CORES

ELTEK

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Dear Customer:

"The Second International Conference on Power Electronics Systems and Applications" will be held in November 2006 in Hong Kong. This conference focuses on the recent research and the industrial projects of power electronics as well as related technology.

In order for us to have well preparation, please help to fill below questionnaire and send back for our reference.

Nov 13th 2006 from 9:00am to 5:00pm

(Please choose interest topic)

Speaker: ALTANA ELECTRICAL INSULATION Asia Business Manager [Rohn Grant](#);

Senior Technical Consultant [Sean McCabe](#) present:

Insulating Materials for High Output power supply applications

Speaker: MICROMETALS INC. President [Jim Cox](#) Present:

Current and New Applications Using Micrometals Iron Powder and 200C SERIES Core Materials

Speaker: ELTEK INTERNATIONAL LABORATORIES President [Ed Van Vooren](#) present:

Electrical Insulation Systems -Various applications from military to automotive to general commercial applications

Speaker: LODESTONE PACIFIC President [Richard Barden](#) present:

Plastic Molding / Transformer bobbin - Cost Savings at the Expense of Quality, Safety, and the Environment

Speaker: DuPont Engineering Polymers - Marketing Manager, [Gregory Lau](#) present:

Introduces Zytel® High temperature Nylon HTN and Zenite® LCP

Speaker: RUBADUE WIRE INC. President [Susan Welsh](#) present:

Triple insulation wire in switching power supply design

Speaker: P.LEO & CO LTD [William Fung](#) Research Centre Officer;

Senior Engineer & EEIC Technical Consultant [Xu Guo Wei](#) present:

Development of BCwire® Magnet Wire & CORONA-R™ Corona Resistant Wire

Speaker: FDK HONG KONG LTD General Manager Fumihito Toyota;
FDK CORPORATION Yukihiro Ota & Shigenori Suzuki present:
Multi-Layer Power Inductor and DC/DC converter

Please list if any comment or suggestion _____

And other keynote and paper submitted from Polytechnic University

Registration fee: 1) HKD\$ 800/day (Non member)

2) IEE, HKIE, IEEE, EEIC, PERC member HKD\$ 400/day

3) Before September succeeds the application to become the EEIC member can enjoy the half price benefit, and automatically gains the exemption EEIC membership until January 2008. Please apply ASAP.

4) EEIC member attends 13th conference can get free participation on Nov 14th FDK conference
(Note: Admission including lunch and snack)

Attendance on November 13th of the conference: _____

	<u>Attendance Name</u>	<u>Title/Department</u>	<u>E-Mail Address</u>
1.	_____	_____	_____
2.	_____	_____	_____

Attendance on November 14th of the conference: _____

	<u>Attendance Name</u>	<u>Title/Department</u>	<u>E-Mail Address</u>
1.	_____	_____	_____
2.	_____	_____	_____

Details please visit HK Polytechnic University website: http://perc.polyu.edu.hk/pesa06/modules/xt_conteudo/?id=1
or EEIC website: http://www.eeic.org/english/news/news_061113.htm

Since the seats are limited, confirmation is subject to our final arrangement.

Please fill this questionnaire and send back to Fax: (852) 26902805; E-Mail: info@eeic.org

Any question, please feel free to contact Ms. Lam at Tel: (852) 26901816

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